

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Akihiko ENDO et al.

Group Art Unit: 2823

Appln. No. : 10/570,663

Examiner: Hsien Ming LEE

I.A. Filed : September 8, 2004

Confirmation No.: 1239

For : METHOD FOR PRODUCING BONDED WAFER

COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

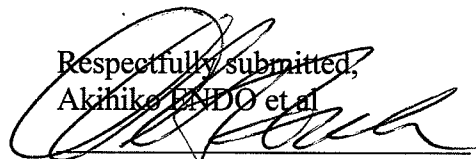
Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop Issue Fee
Randolph Building
401 Dulany Street
Alexandria VA 22314

Sir:

In response to the Notice of Allowability, mailed by the U.S. Patent and Trademark Office on July 18, 2008 and to the Statement of Reasons for Allowance attached thereto, Applicants wish to clarify the record with respect to the basis for the patentability of claims in the present application. In this regard, while Applicants do not disagree with the Examiner's indication of allowability, Applicants submit that each of the claims in the present application recite a combination of features, and that the basis for patentability of each of these claims is based on the combination of features recited therein.

Should there be any questions, the Examiner is invited to contact the undersigned at the below-listed telephone number.

Respectfully submitted,
Akihiko ENDO et al



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September 29, 2008
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